

METHOD OF FORMING CONDUCTOR WIRING PATTERN

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ABSTRACT OF THE DISCLOSURE

A method of forming a conductor wiring pattern comprises: forming a first insulating layer on a surface 10 of a semiconductor wafer and also forming a second, photosensitive insulating resin layer thereon; light-exposing and developing the second insulating layer to form pattern grooves so that the first insulating layer is exposed at bottoms of the pattern grooves; forming a 15 plating seed layer on the second insulating layer including inner surfaces of the pattern grooves and then forming a resist pattern on the seed layer except for portions of the pattern grooves; filling the pattern grooves with a conductor by an electrolytic plating using 20 the seed layer as a power supply layer; and removing the resist pattern and also removing the seed layer exposed on the surface of the second insulating layer to form a wiring pattern consisting of conductors remaining in the pattern grooves.